

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	37596	(semiconductor near (device or element)) and (high near density)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/10/10 06:39
L2	9800	(semiconductor near (device or element)) same (high near density)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/10/10 07:24
L3	8329	29/417,592.1,593,831,842,846,854.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/10/10 07:21
L4	2185	29/25.01.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/10/10 07:21
L5	1832	438/6,15,337,462.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/10/10 07:27
L6	10499	3 or 4	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/10/10 07:22
L7	57	2 and 5	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/10/10 07:22
L8	94	2 and 6	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/10/10 07:24
L9	3615	427/129,130.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/10/10 07:24
L10	0	2 and 9	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/10/10 07:24
L11	409663	(semiconductor near (device or element))	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/10/10 07:45
L12	24	9 and 11	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/10/10 07:25
L13	173	7 or 8 or 12	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/10/10 07:25
L14	0	7 and 8 and 12	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/10/10 07:25
L15	1737	protrud\$3 same (contact near terminal)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/10/10 07:26

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L16	950	protrud\$3 with (contact near terminal)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/10/10 07:26
L17	1	13 and 16	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/10/10 07:26
L18	7451	438/14-18.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/10/10 07:27
L19	140549	semiconductor with (integrated near circuit)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/10/10 07:28
L20	4	("5055778" "5532906" "5672977" "5945834").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/10 07:28
L21	37	("5945834").URPN.	USPAT	OR	ON	2006/10/10 07:30
L22	1048	WADA-YUJI.in. or KASUKABE-SUSUMU.in. or HASEBE-TAKEHIKO.in. or NARIZUKA-YASUNORI.in. or YABUSHITA-AKIRA.in. or MORI-TERUTAKA.in. or HASEBE-AKIO.in. or MOTOYAMA-YASUHIRO.in. or SHOJI-TERUO.in. or SUEYOSHI-MASAKAZU.in.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/10/10 07:36
L23	99	19 and 22	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/10/10 07:37
L24	8	16 and 23	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/10/10 07:45
L25	10635	324/754,755,758,761,765.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/10/10 07:45
L26	15955	test\$3 with (semiconductor near (device or element))	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/10/10 07:46
L27	152	25 and "265"	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/10/10 07:46
L28	2316	25 and 26	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/10/10 07:46
L29	13	22 and 28	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/10/10 07:46

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L30	2	16 and 29	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/10/10 07:46
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IEEE JNL IEEE Journal or Magazine

IEEE JNL IEE Journal or Magazine

IEEE CNF IEEE Conference Proceeding

IEEE CNF IEE Conference Proceeding

IEEE STD IEEE Standard

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- ☐ 1. **Replaceable chip module (RCM™)**
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